RJK2009DPM

Silicon N Channel MOS FET
High Speed Power Switching

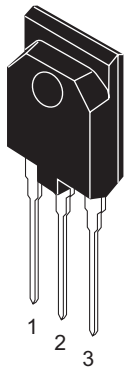
REJ03G0474-0200
Rev.2.00
Aug.09.2005

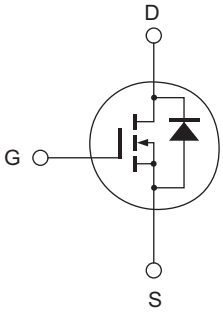
Features

- Low on-resistance
- Low leakage current
- High speed switching

Outline

RENESAS Package code: PRSS0003ZA-A
(Package name: TO-3PFM)





1. Gate
2. Drain
3. Source

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	200	V
Gate to source voltage	V_{GSS}	±30	V
Drain current	I_D	40	A
Drain peak current	$I_{D\ (pulse)}$ Note1	160	A
Body-drain diode reverse drain current	I_{DR}	40	A
Body-drain diode reverse drain peak current	$I_{DR\ (pulse)}$ Note1	160	A
Avalanche current	I_{AP} Note3	40	A
Avalanche energy	E_{AR} Note3	106	mJ
Channel dissipation	Pch Note2	60	W
Channel to case thermal impedance	θch-c	2.08	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	–55 to +150	°C

Notes: 1. PW ≤ 10 µs, duty cycle ≤ 1%
2. Value at Tc = 25°C
3. STch = 25°C, Tch ≤ 150°C

Electrical Characteristics

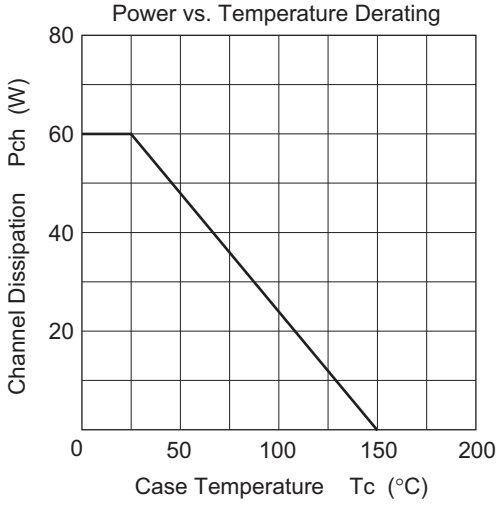
(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	200	—	—	V	I_D = 10 mA, V_{GS} = 0
Zero gate voltage drain current	I_{DSS}	—	—	1	µA	V_{DS} = 200 V, V_{GS} = 0
Gate to source leak current	I_{GSS}	—	—	±0.1	µA	V_{GS} = ±30 V, V_{DS} = 0
Gate to source cutoff voltage	$V_{GS(off)}$	3.0	—	4.5	V	V_{DS} = 10 V, I_D = 1 mA
Forward transfer admittance	$\|y_{fs}\|$	20	33	—	S	I_D = 20 A, V_{DS} = 10 V Note4
Static drain to source on state resistance	$R_{DS(on)}$	—	0.029	0.036	Ω	I_D = 20 A, V_{GS} = 10 V Note4
Input capacitance	Ciss	—	2900	—	pF	V_{DS} = 25 V, V_{GS} = 0, f = 1 MHz
Output capacitance	Coss	—	520	—	pF	
Reverse transfer capacitance	Crss	—	66	—	pF	
Turn-on delay time	$t_{d(on)}$	—	40	—	ns	I_D = 20 A, V_{GS} = 10 V, R_L = 5 Ω, Rg = 10 Ω
Rise time	t_r	—	160	—	ns	
Turn-off delay time	$t_{d(off)}$	—	120	—	ns	
Fall time	t_f	—	110	—	ns	
Total gate charge	Qg	—	72	—	nC	V_{DD} = 160 V, V_{GS} = 10 V, I_D = 40 A
Gate to source charge	Qgs	—	16	—	nC	
Gate to drain charge	Qgd	—	31	—	nC	
Body-drain diode forward voltage	V_{DF}	—	0.9	1.4	V	I_F = 40 A, V_{GS} = 0 Note4
Body-drain diode reverse recovery time	t_{rr}	—	150	—	ns	I_F = 40 A, V_{GS} = 0, diF/dt = 100 A/µs
Body-drain diode reverse recovery charge	Q_{rr}	—	0.8	—	µC	

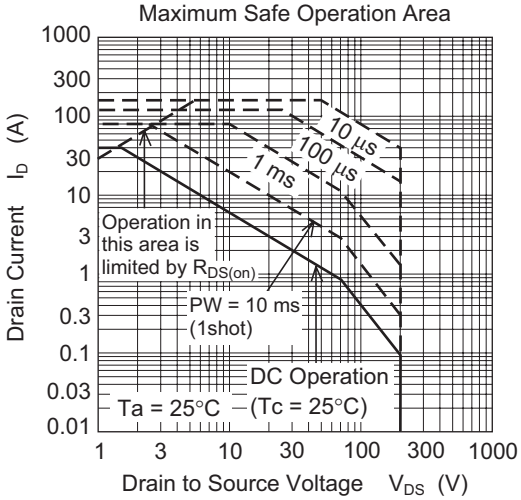
Notes: 4. Pulse test

Main Characteristics

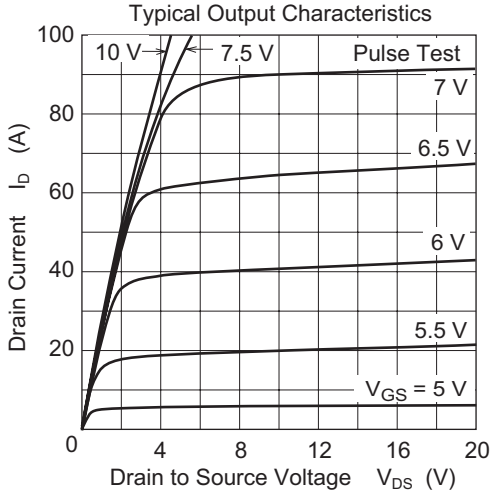
Power vs. Temperature Derating



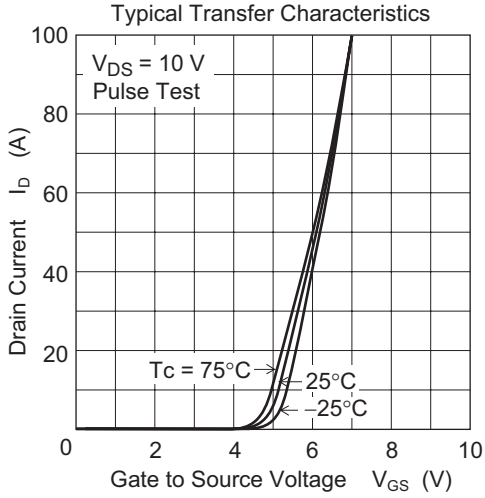
Maximum Safe Operation Area



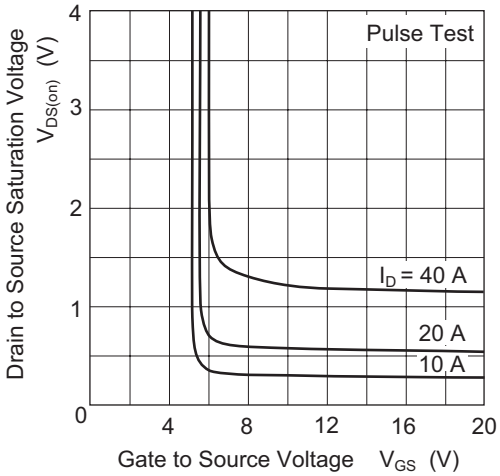
Typical Output Characteristics



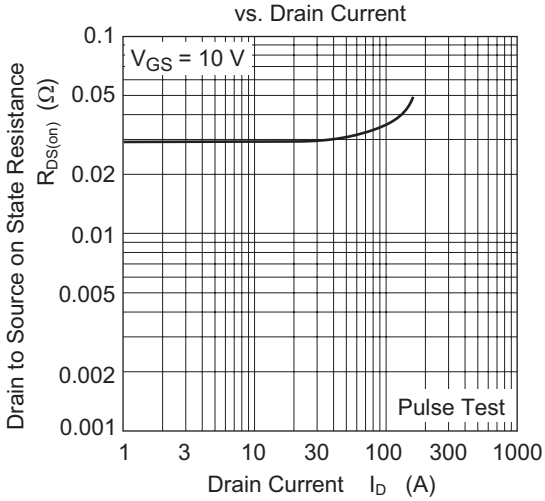
Typical Transfer Characteristics



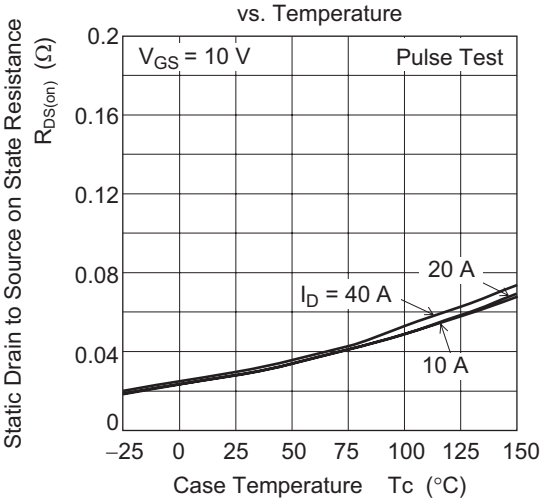
Drain to Source Saturation Voltage vs. Gate to Source Voltage



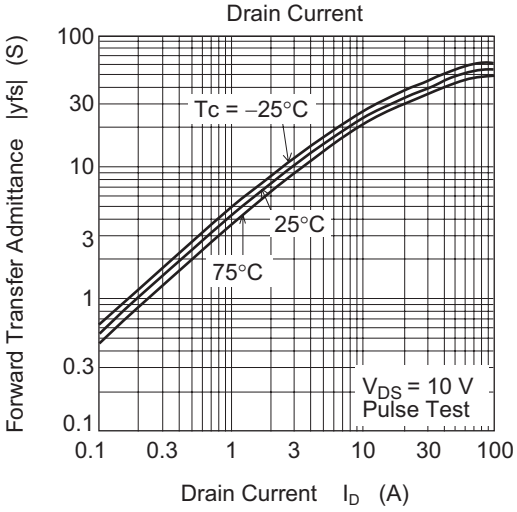
Static Drain to Source on State Resistance vs. Drain Current



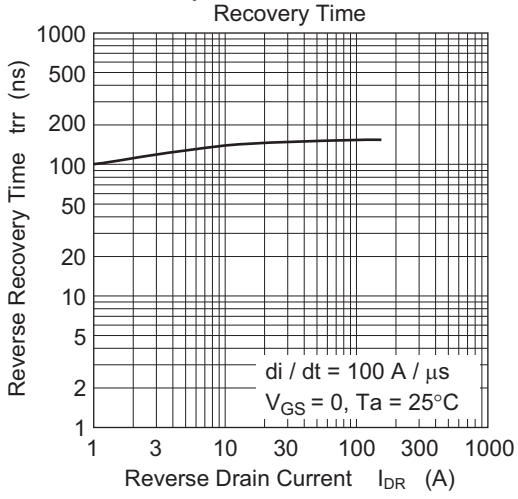
Static Drain to Source on State Resistance vs. Temperature



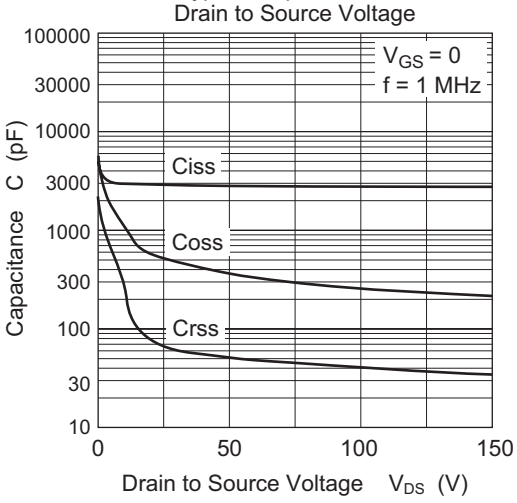
Forward Transfer Admittance vs. Drain Current



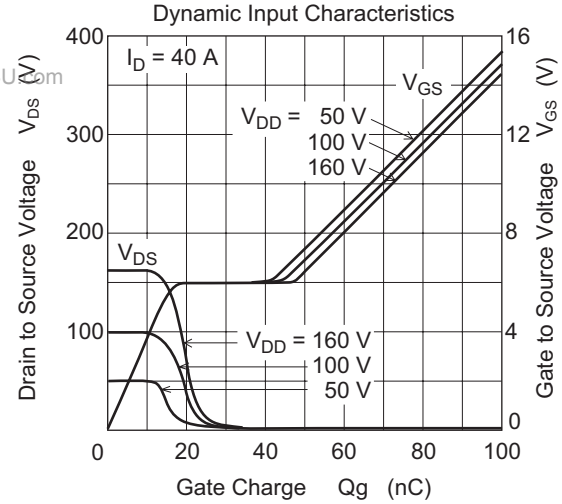
Body-Drain Diode Reverse Recovery Time



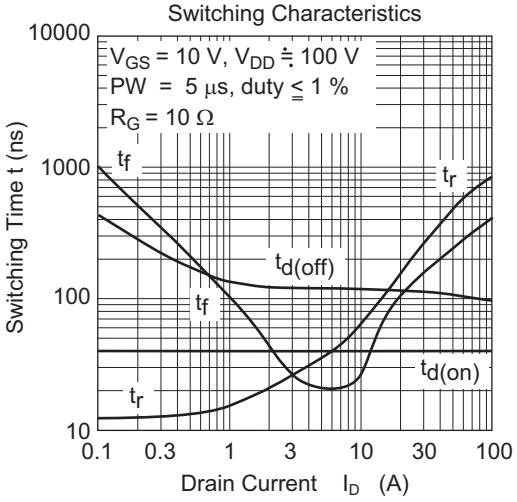
Typical Capacitance vs. Drain to Source Voltage



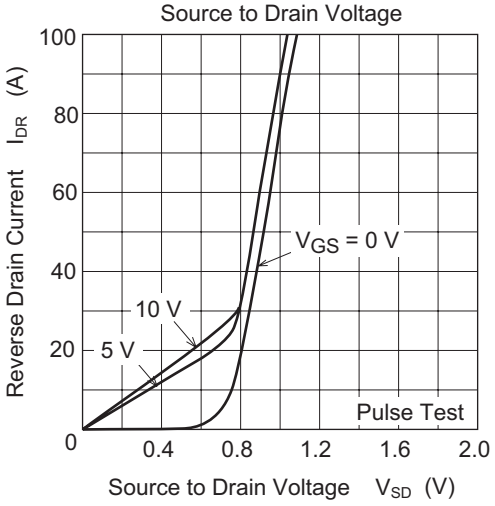
Dynamic Input Characteristics



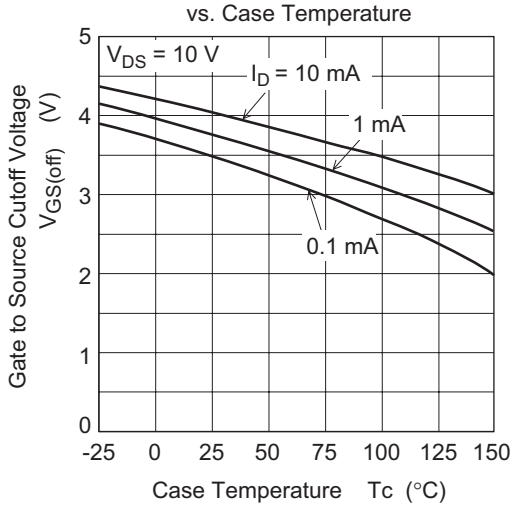
Switching Characteristics



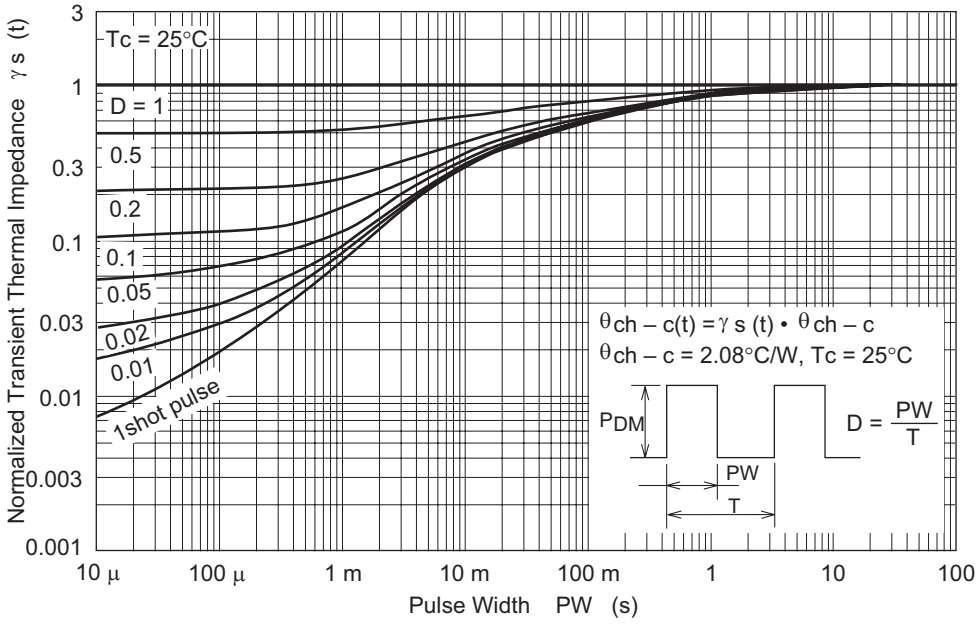
Reverse Drain Current vs. Source to Drain Voltage



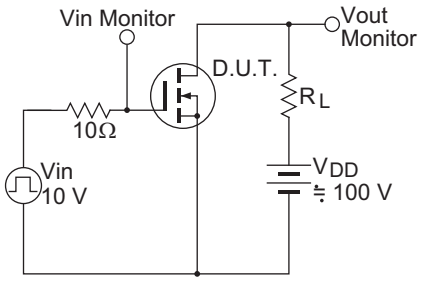
Gate to Source Cutoff Voltage vs. Case Temperature



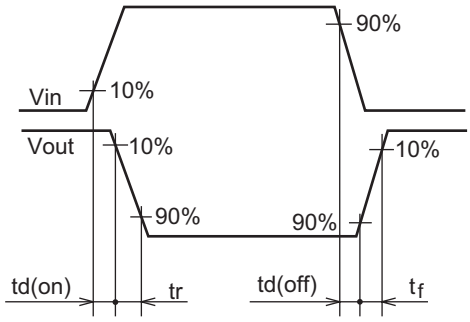
Normalized Transient Thermal Impedance vs. Pulse Width



Switching Time Test Circuit



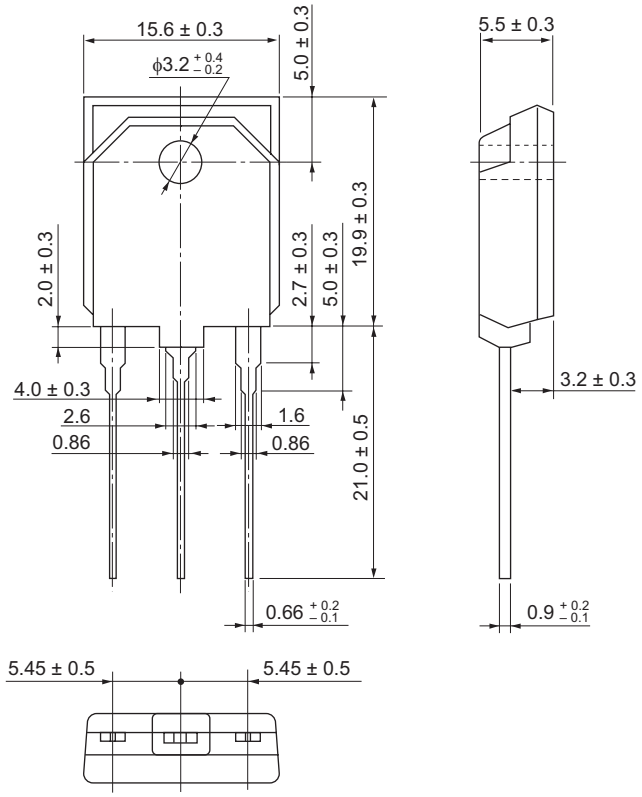
Waveform



Package Dimensions

JEITA Package Code	RENESAS Code	Package Name	MASS[Typ.]
SC-93	PRSS0003ZA-A	TO-3PFM / TO-3PFMV	5.2g

Unit: mm



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Part Name	Quantity	Shipping Container
RJK2009DPM-E	30 pcs	Plastic magazine

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